

Technical Data Sheet

MODEL NO: S282ANG4-JH

0402Package 1.0*0.5mm Chip LEDs

Features:

•Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

Applications:

Indicators

•Automotive : backlighting in dashboard and switch

•Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Pure-green	Water Clear

Electrical/Optical Characteristics(Ta=25°C)

Parameter	Test	Value			Unit	
	Condition	Symbol	Min	Тур	Мах	Unit
Spectral half bandwidth	IF=2mA	$ riangle \lambda$		35		nm
Dominant wavelength	IF=20mA	λD	520		530	nm
Forward voltage	IF=20mA	VF	2.8		3.6	V
Luminous intensity	IF=20mA	lv	320	500	800	mcd
Viewing angle at 50% Iv	IF=20mA	2 <i>θ</i> 1/2		120		Deg
Reverse current	Vr=5V	lr			10	μΑ

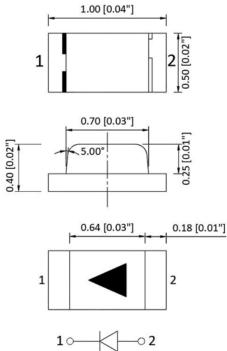


Absolute Maximum Ratings(Ta= 25° C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	60	mW
Forward current	lf	25	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	FP	125	mA

PACKAGING DIMENSIONS (mm):

Package outlines



Recommend Pad Layout

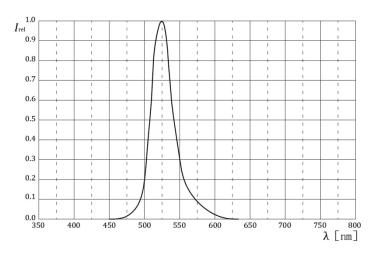




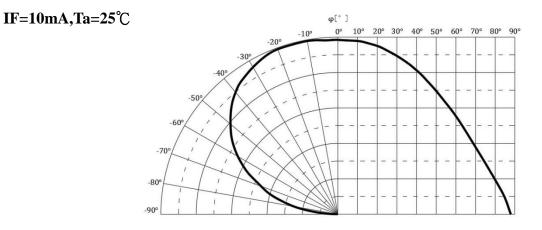
Typical Electro-Optical Characteristics Curve:

Relative Spectral Emission

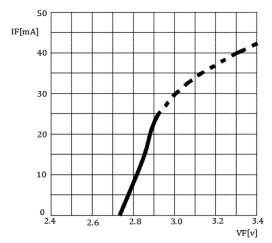
IF=5mA,Ta=25°C

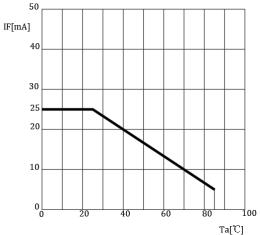


Radiation Characteristics



Forward Current vsForward Voltage Forward Current Derating Curve $Ta{=}25^\circ\!\mathrm{C}$







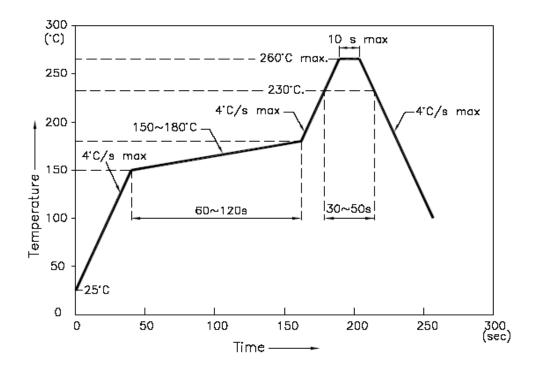
Precautions For Use :

Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C ~ 30° C , 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}C\pm 5^{\circ}C$ for 15 hrs.
- Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245^{\circ}C(\pm 5^{\circ}C)$.the maximum soldering temperature should be limited to $260^{\circ}C$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

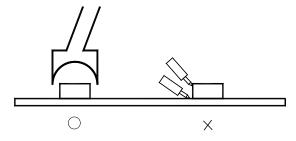


■Soldering iron

Basic spec is ≤ 5 sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

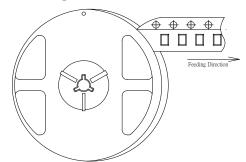
Rework

- 1. Customer must finish rework within 5 sec under 260° C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



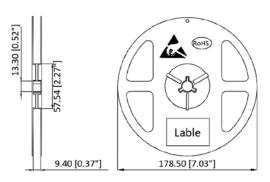


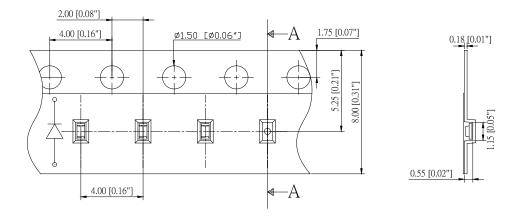
Feeding Direction



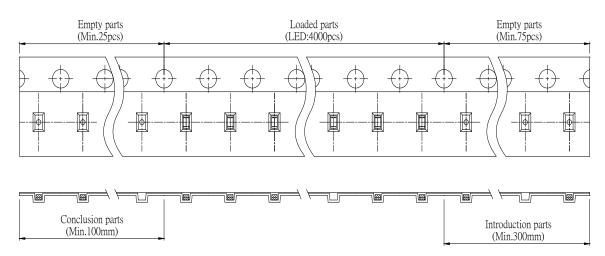
■Dimensions of Tape (Unit: mm)

• Dimensions of Reel (Unit: mm)





■Arrangement of Tape



■Note

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two.
- 3. 4,000 pcs/Reel.